



## 60V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

# **Product Summary**

BV <sub>DSS</sub>	Rds(on)	I <sub>D</sub> T <sub>C</sub> = +25°C
60V	$16m\Omega @ V_{GS} = 10V$	37.1A
60 V	$24m\Omega$ @ $V_{GS} = 4.5V$	30.3A

# **Description and Applications**

This MOSFET is designed to minimize the on-state resistance (RDS(ON)) and maintain superior switching performance, making it ideal for highefficiency power-management applications.

- Power managements
- DC-DC converters
- Motor controls

### Site 1:

Site 2:







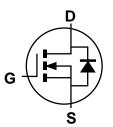
Top View **Bottom View** 

# **Features**

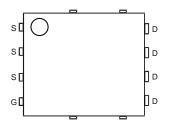
- Rated to +175°C Ideal for High Ambient Temperature
- 100% Unclamped Inductive Switching Ensures More Reliable and Robust End Application
- High Conversion Efficiency
- Low RDS(ON) Minimizes On-State Losses
- Low Input Capacitance
- Fast Switching Speed
- Thermally Efficient Package Cooler Running Applications
- <1.1mm Package Profile Ideal for Thin Applications
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- An automotive-compliant part is available under separate datasheet (DMTH6016LPSQ)

# **Mechanical Data**

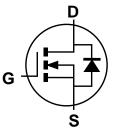
- Package: PowerDI®5060-8
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.097 grams (Approximate)



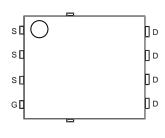
Internal Schematic



Top View Pin Configuration



Internal Schematic



Top View Pin Configuration

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.



# Ordering Information (Note 4)

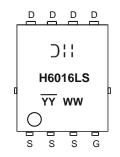
Part Number	Package	Packing		
Fait Number	Fackage	Qty.	Carrier	
DMTH6016LPS-13	PowerDI5060-8	2,500	Tape & Reel	
DMTH6016LPS-13	PowerDI5060-8/SWP (Type UX)	2,500	Tape & Reel	

Note:

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

# **Marking Information**





☐ He Manufacturer's Marking
H6016LS = Product Type Marking Code
YYWW = Date Code Marking
YY or YY = Last Two Digits of Year (ex: 23 = 2023)
WW = Week Code (01 to 53)

# **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			VDSS	60	V
Gate-Source Voltage			Vgss	±20	V
Continuous Drain Current (Note 6) $V_{GS} = 10V$ $T_C = +25^{\circ}C$ $T_C = +100^{\circ}C$		lo	37.1 26.2	А	
Continuous Drain Current (Note 5) V <sub>GS</sub> = 10V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +100°C	I <sub>D</sub>	10.6 7.5	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			IDM	145	Α
Maximum Continuous Body Diode Forward Current (Note 6)			Is	31	Α
Avalanche Current, L = 0.1mH			las	15.3	Α
Avalanche Energy, L = 0.1mH			Eas	11.7	mJ

# **Thermal Characteristics**

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T <sub>A</sub> = +25°C	PD	3	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	Reja	49	°C/W
Total Power Dissipation (Note 6)	Tc = +25°C	PD	37.5	W
Thermal Resistance, Junction to Case (Note 6)		Rejc	4	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +175	°C

s: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.

6. Thermal resistance from junction to soldering point (on the exposed drain pad).

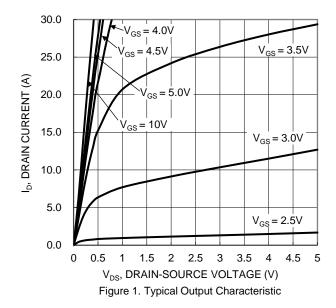


# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BVDSS	60		_	V	$V_{GS} = 0V, I_{D} = 250\mu A$	
Zero Gate Voltage Drain Current	IDSS	_	_	1	μΑ	V <sub>DS</sub> =48V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	Vgs(TH)	1	_	2.5	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
Static Drain-Source On-Resistance	Descou	_	12.4	16	mΩ	$V_{GS} = 10V, I_{D} = 20A$	
Static Dialii-Source Off-Resistance	RDS(ON)	_	18.2	24	11122	$V_{GS} = 4.5V, I_{D} = 18A$	
Diode Forward Voltage	$V_{SD}$	_	0.7	1.2	V	$V_{GS} = 0V$ , $I_{S} = 1A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss	_	864	_		V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V, f = 1MHz	
Output Capacitance	Coss	_	282	_	pF		
Reverse Transfer Capacitance	Crss	_	27	_			
Gate Resistance	Rg	_	1.3	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (Vgs = 4.5V)	Qg	_	8.4	_			
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	17	_	nC	V <sub>DS</sub> = 30V, I <sub>D</sub> = 10A	
Gate-Source Charge	Q <sub>gs</sub>	_	3.1	_	nc nc		
Gate-Drain Charge	Qgd	_	4.3	_			
Turn-On Delay Time	t <sub>D(ON)</sub>	_	3.4	_		$V_{GS} = 10V, V_{DS} = 30V,$ $R_{G} = 6\Omega, I_{D} = 10A$	
Turn-On Rise Time	tR	_	5.2	_	ns		
Turn-Off Delay Time	tD(OFF)	_	13	_			
Turn-Off Fall Time	tr	_	7	_			
Reverse Recovery Time	trr	_	22	_	ns	104 11/11 1004/	
Reverse Recovery Charge	Q <sub>RR</sub>	_	11	_	nC	I <sub>F</sub> = 10A, di/dt = 100A/μs	

7. Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to product testing. Notes:





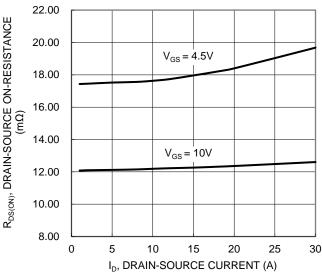


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

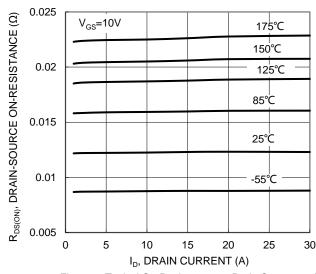


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

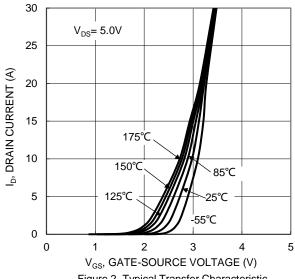


Figure 2. Typical Transfer Characteristic

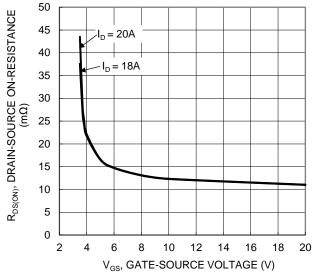


Figure 4. Typical Transfer Characteristic

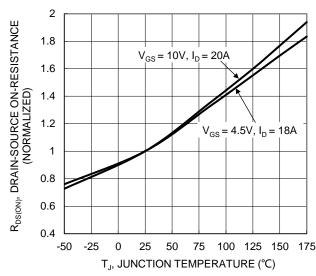


Figure 6. On-Resistance Variation with Temperature



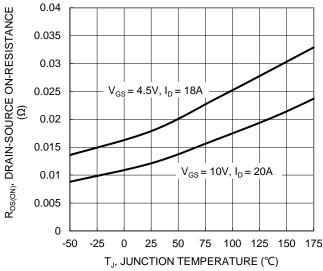


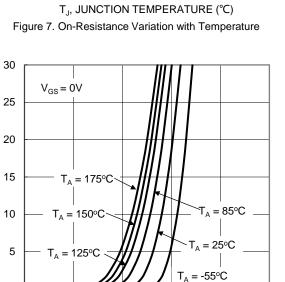
Is, SOURCE CURRENT (A)

0

0

0.3





V<sub>SD</sub>, SOURCE-DRAIN VOLTAGE (V) Figure 9. Diode Forward Voltage vs. Current

0.6

0.9

1.2

1.5

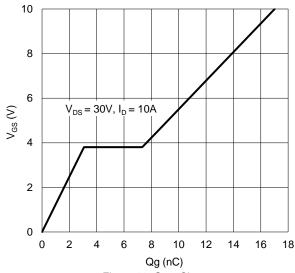


Figure 11. Gate Charge

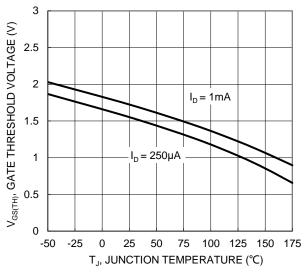
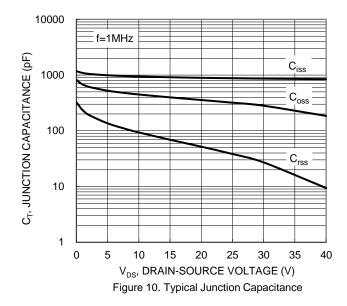


Figure 8. Gate Threshold Variation vs. Junction Temperature



1000 R<sub>DS(ON)</sub> LIMITED 100 ID, DRAIN CURRENT (A) 10 P<sub>W</sub>=100μs  $T_{J(Max)}=175$ °C T<sub>C</sub>=25°C 0.1 Single Pulse DUT on infinite heatsink V<sub>GS</sub>=10V 0.01 100 V<sub>DS</sub>, DRAIN-SOURCE VOLTAGE (V) Figure 12. SOA, Safe Operation Area



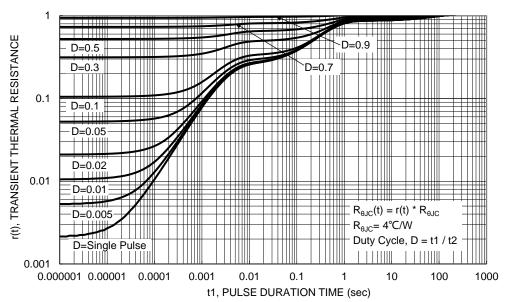


Figure 13. Transient Thermal Resistance



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### Site 1:

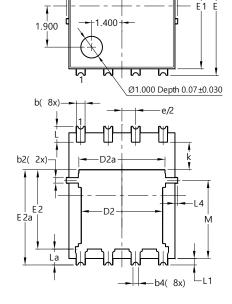
# Detail A Detail A Detail A B ( 4X) B ( 4X) Detail A Detail A Detail A G Detail A Detail A Detail A Detail A

PowerDI5060-8				
Dim	Min	Max	Тур	
Α	0.90	1.10	1.00	
A1	0.00	0.05	_	
b	0.33	0.51	0.41	
b2	0.200	0.350	0.273	
b3	0.40	0.80	0.60	
С	0.230	0.330	0.277	
D		5.15 BSC	;	
D1	4.70	5.10	4.90	
D2	3.70	4.10	3.90	
D3	3.90	4.30	4.10	
E	(	6.15 BSC	;	
E1	5.60	6.00	5.80	
E2	3.28	3.68	3.48	
E3	3.99	4.39	4.19	
е		1.27 BSC	;	
G	0.51	0.71	0.61	
K	0.51	_	_	
L	0.51	0.71	0.61	
L1	0.100	0.200	0.175	
М	3.235	4.035	3.635	
M1	1.00	1.40	1.21	
Θ	10°	12°	11°	
Θ1	6°	8°	7°	
All Dimensions in mm				

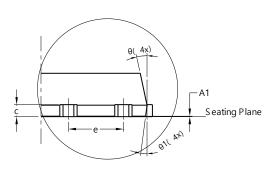
Site 2:

# PowerDI5060-8/SWP (Type UX)

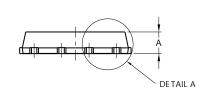
PowerDI5060-8



-D1



DETAIL A



PowerDI5060-8/SWP (Type UX)				
Dim	Min	Max	Тур	
Α	0.90	1.10	1.00	
A1	0	0.05		
b	0.30	0.50	0.41	
b2	0.20	0.35	0.25	
b4		).25REF		
С	0.230	0.330	0.277	
C D	5	.15 BS0		
D1	4.70	5.10	4.90	
D2	3.56	3.96	3.76	
D2a	3.78	4.18	3.98	
Е	6	.40 BS0	)	
E1	5.60	6.00	5.80	
E2	3.46	3.86	3.66	
E2a	4.195	4.595	4.395	
е		.27BSC	<u> </u>	
k	1.05			
L	0.635	0.835	0.735	
La	0.635	0.835	0.735	
L1	0.200	0.400	0.300	
L1a	0.050REF			
L4	0.025	0.225	0.125	
М	3.205	4.005	3.605	
θ	10°	12°	11°	
θ1	6°	8°	7°	
All Dimensions in mm				

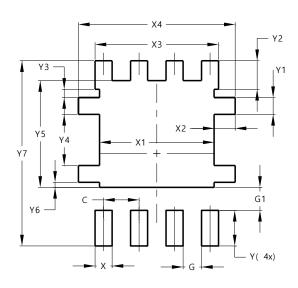


# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

Site 1:

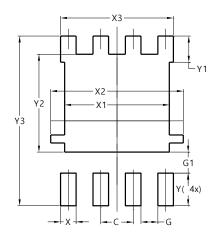
# PowerDI5060-8



Dimensions	Value (in mm)
С	1.270
G	0.660
G1	0.820
X	0.610
X1	4.100
X2	0.755
Х3	4.420
X4	5.610
Y	1.270
Y1	0.600
Y2	1.020
Y3	0.295
Y4	1.825
Y5	3.810
Y6	0.180
Y7	6.610

Site 2:

# PowerDI5060-8/SWP (Type UX)



Dimensions	Value (in mm)
С	1.270
G	0.660
G1	0.820
X	0.610
X1	4.100
X2	5.190
Х3	4.420
Y	1.270
Y1	1.020
Y2	3.810
Y3	6.610



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